

Amendments to the Claims

OK to enter NIN 3/15/05
1-11. (Cancelled)

12. (Currently Amended) ~~The process according to claim 4~~ A process for reducing a surface defect of a magnetic disk substrate comprising applying to a magnetic disk substrate or a polishing pad a polishing composition comprising an abrasive, an acid and/or a salt thereof, and water, wherein copper (Cu) is contained in an amount of 1 mg or less per kg of the polishing composition fed to the substrate or the polishing pad, wherein a pH of the polishing composition is 4.0 or less.

13. (Currently Amended) ~~The process according to claim 4, wherein members to be contacted with the polishing composition in the polishing step are made of a metal coated with a resin or made of a resin~~ A process for reducing a surface defect of a magnetic disk substrate comprising applying to a magnetic disk substrate or a polishing pad a polishing composition comprising an abrasive, an acid and/or a salt thereof, and water, wherein copper (Cu) is contained in an amount of 1 mg or less per kg of the polishing composition fed to the substrate or the polishing pad, wherein a pH of the polishing composition is 4.0 or less and wherein prior to or

during applying the polishing composition to the magnetic disk substrate or the polishing pad, the polishing composition is in contact with a member that is made of a metal coated with a resin or that is made of a resin.

14-15. (Cancelled)

16. (Currently Amended) ~~The process according to claim 5~~ A process for manufacturing a magnetic disk substrate comprising a polishing step comprising applying to a magnetic disk substrate or a polishing pad a polishing composition comprising an abrasive, an acid and/or a salt thereof, and water, wherein copper (Cu) is contained in an amount of 1 mg or less per kg of the polishing composition fed to the substrate or the polishing pad, wherein a pH of the polishing composition is 4.0 or less.

17. (Cancelled)

18. (NEW) The process according to claim 12, wherein the abrasive comprises silica particles and a content of the abrasive is 1 to 15% by weight.

19. (NEW) The process according to claim 12, wherein copper (Cu) is contained in an amount of 0.07 mg or less per kg of the polishing composition.

20. (NEW) The process according to claim 12, wherein said magnetic disk substrate having has Ni element on a surface thereof.

21. (NEW) The process according to claim 13, wherein said magnetic disk substrate having has Ni element on a surface thereof.

22. (NEW) The process according to claim 16, wherein the abrasive comprises silica particles and a content of the abrasive is 1 to 15% by weight.

23. (NEW) The process according to claim 16, wherein copper (Cu) is contained in an amount of 0.07 mg or less per kg of the polishing composition.

24. (NEW) The process according to claim 16, wherein prior to or during applying the polishing composition to the magnetic disk substrate or the polishing pad, the polishing composition is in contact with a member that is made of a metal coated with a resin or that is made of a resin.

25. (NEW) The process according to claim 16, wherein said magnetic disk substrate having has Ni element on a surface thereof.